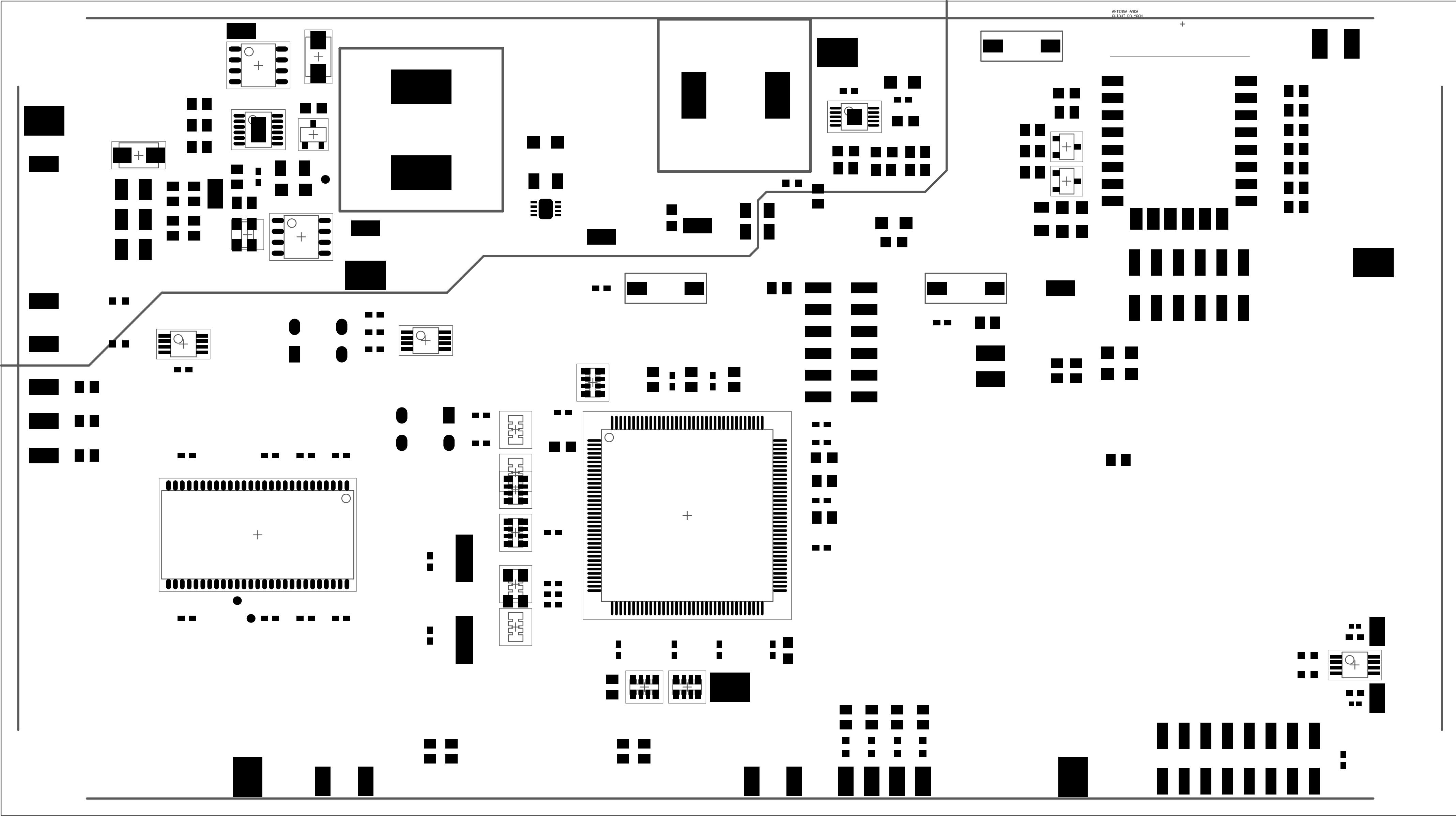
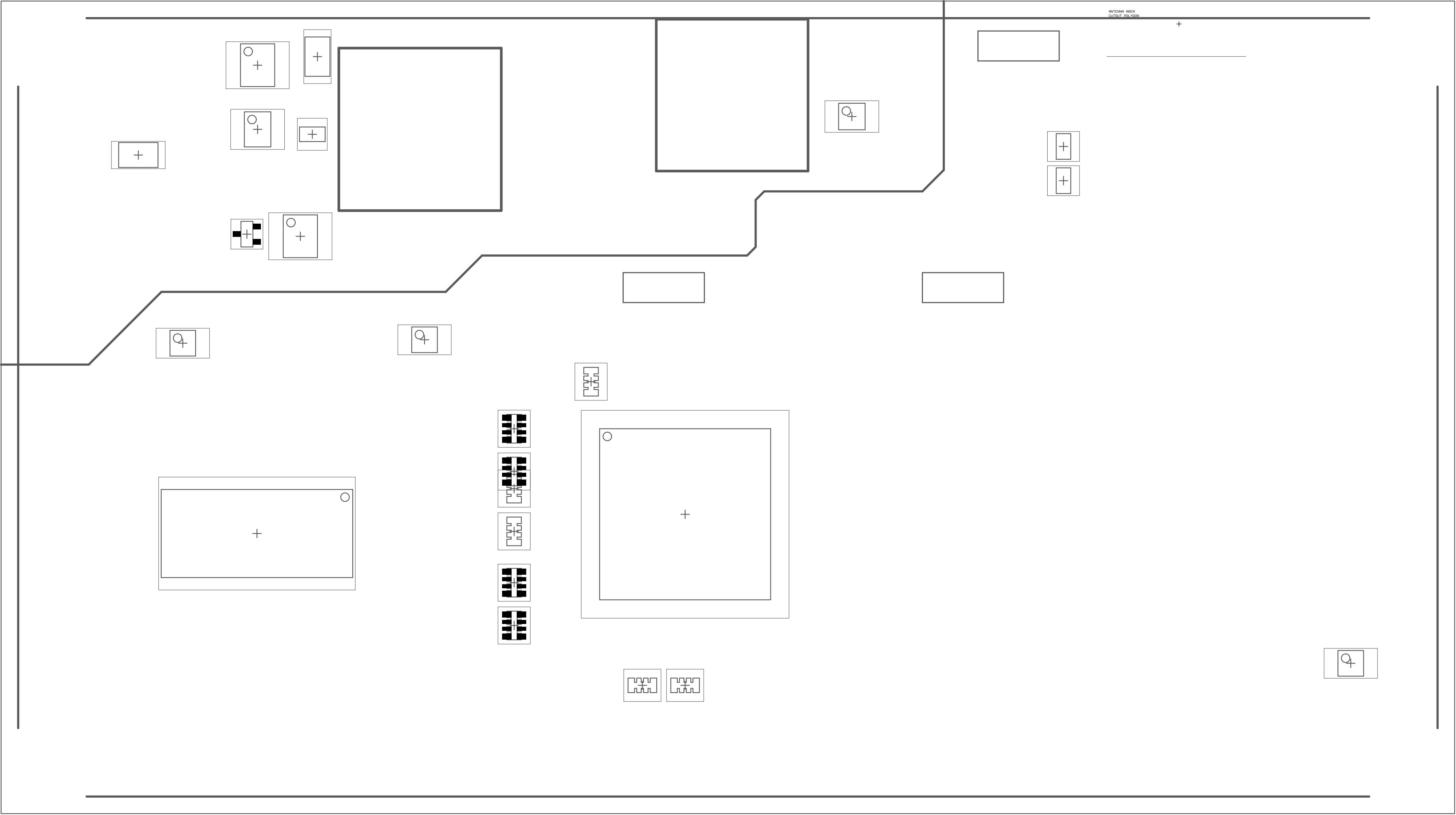


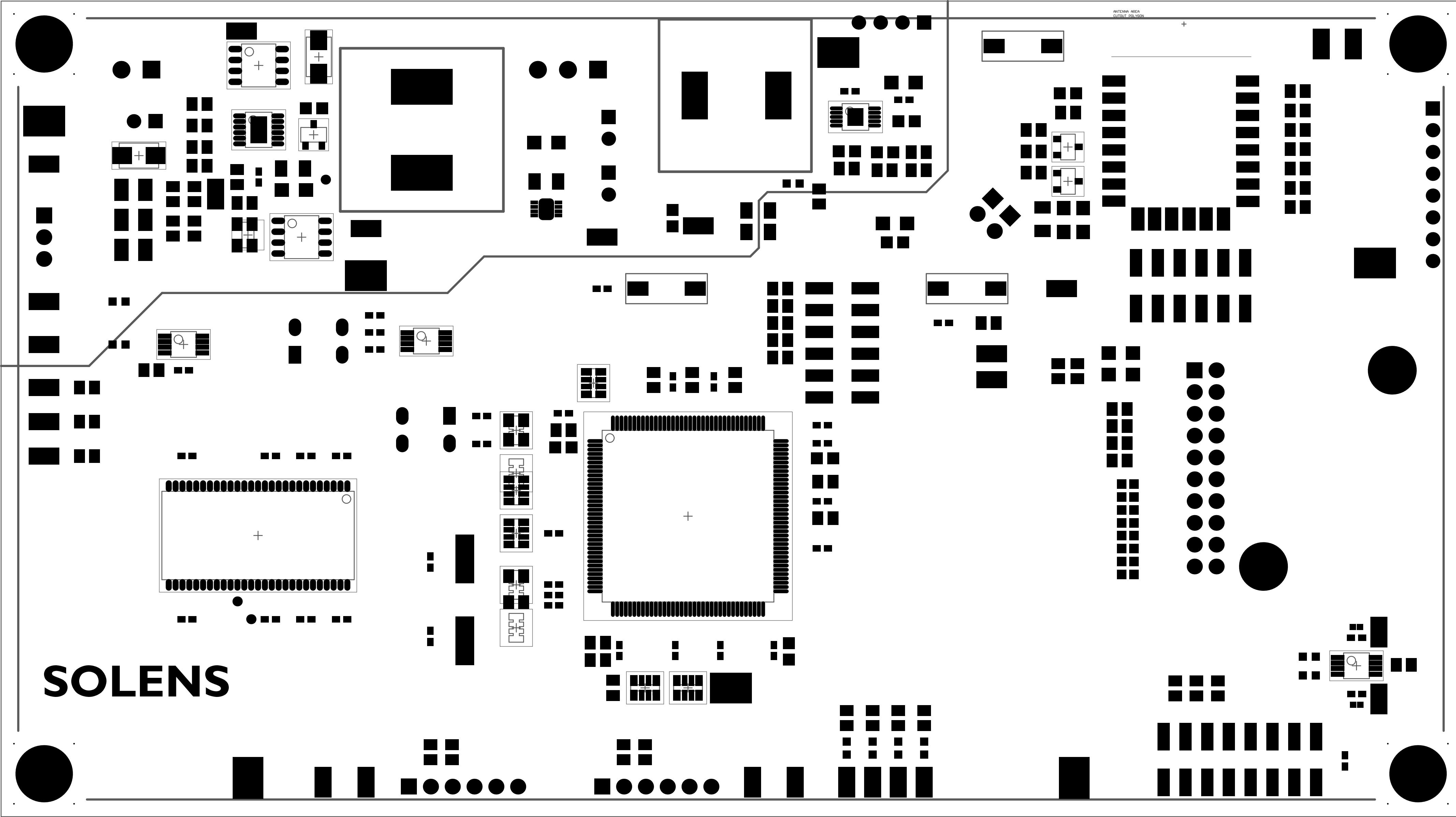
# Board Stack Report

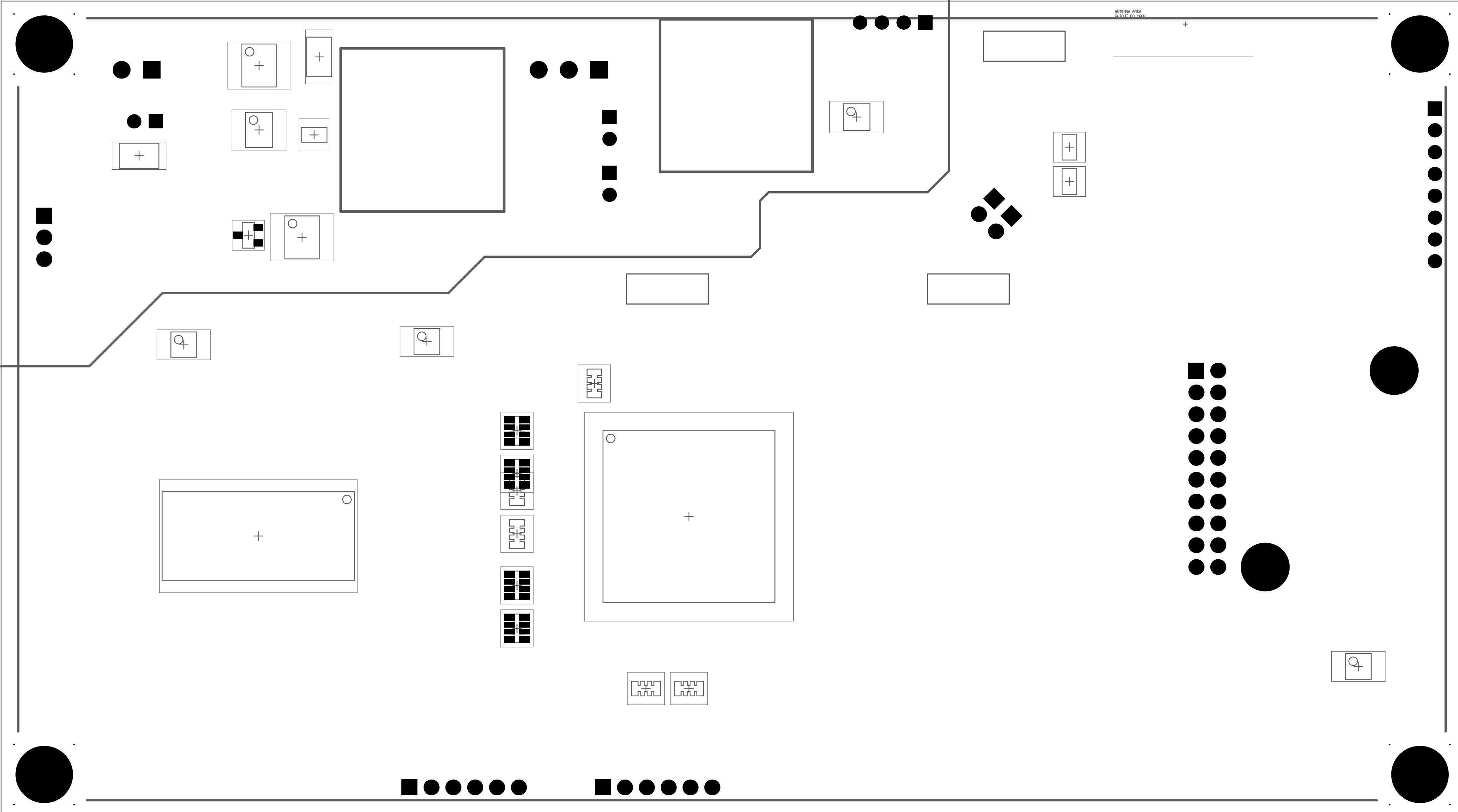
Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.37mil	
5		Dielectric 1	2x2116	9.80mil	4.2
6		Signal Layer 2	Copper	1.37mil	
7		Dielectric 4		40.00mil	4.2
8		Signal Layer 1	Copper	1.37mil	
9		Dielectric 3	2x2116	9.80mil	4.2
10		Bottom Layer	Copper	1.37mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
Height : 65.88mil					

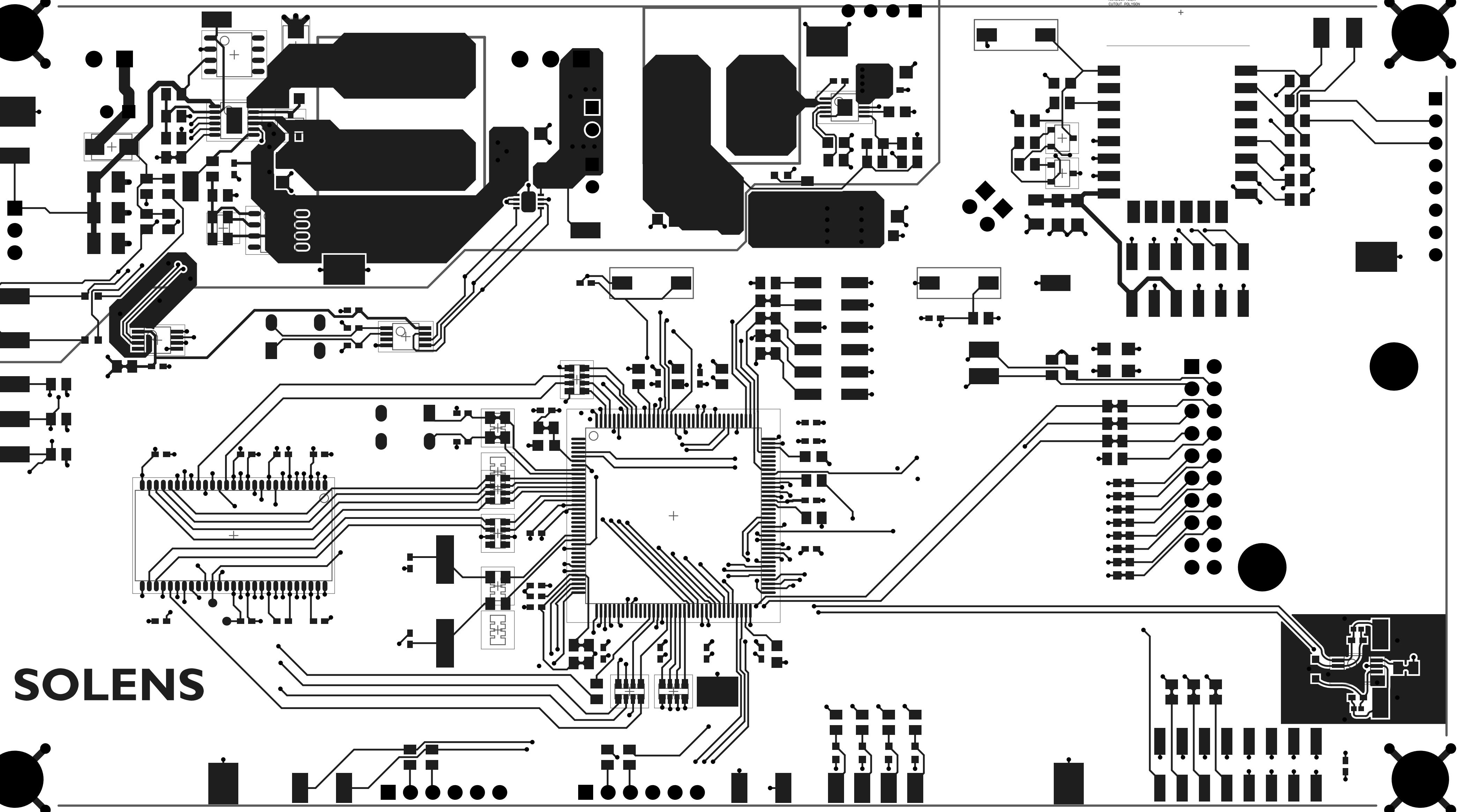


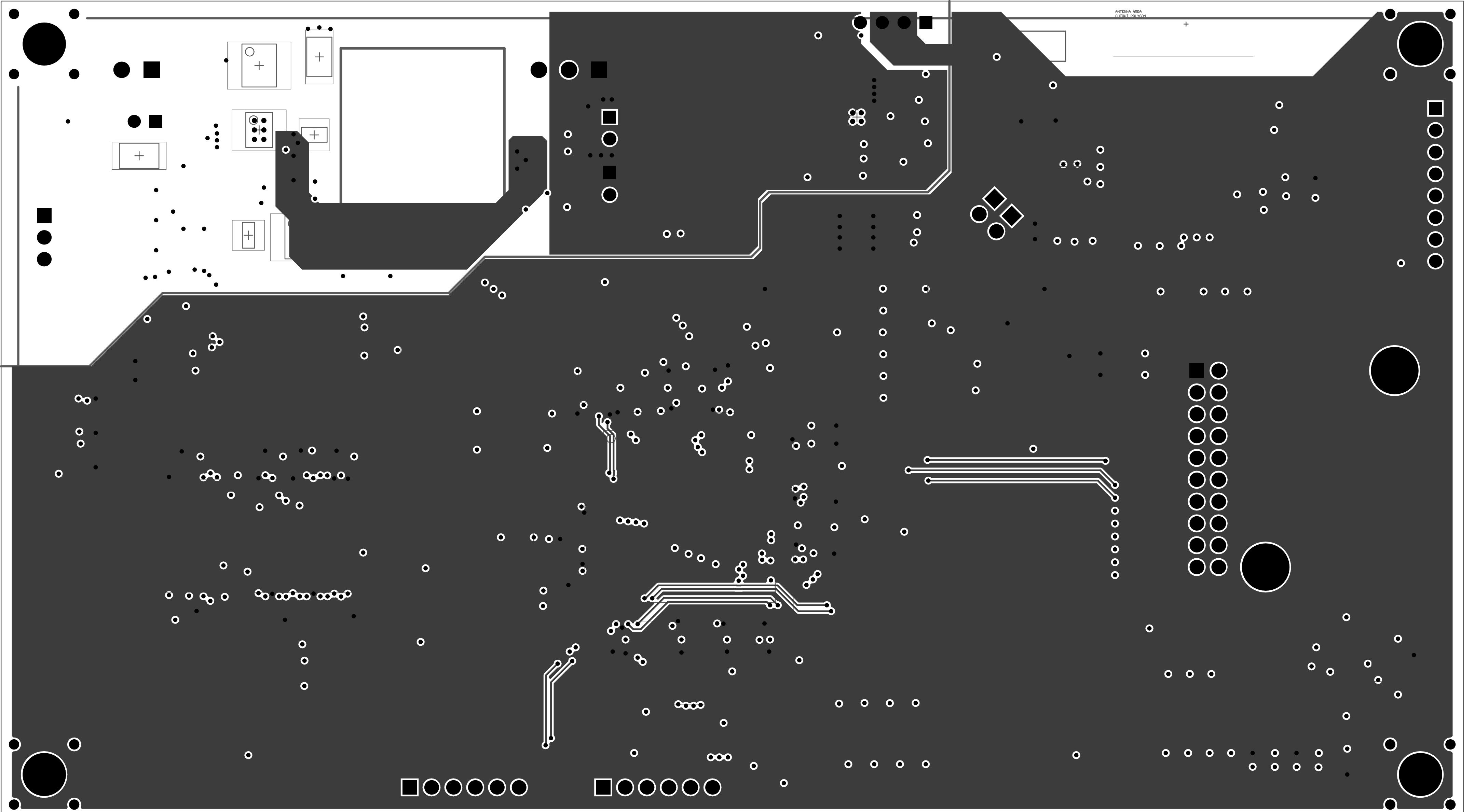


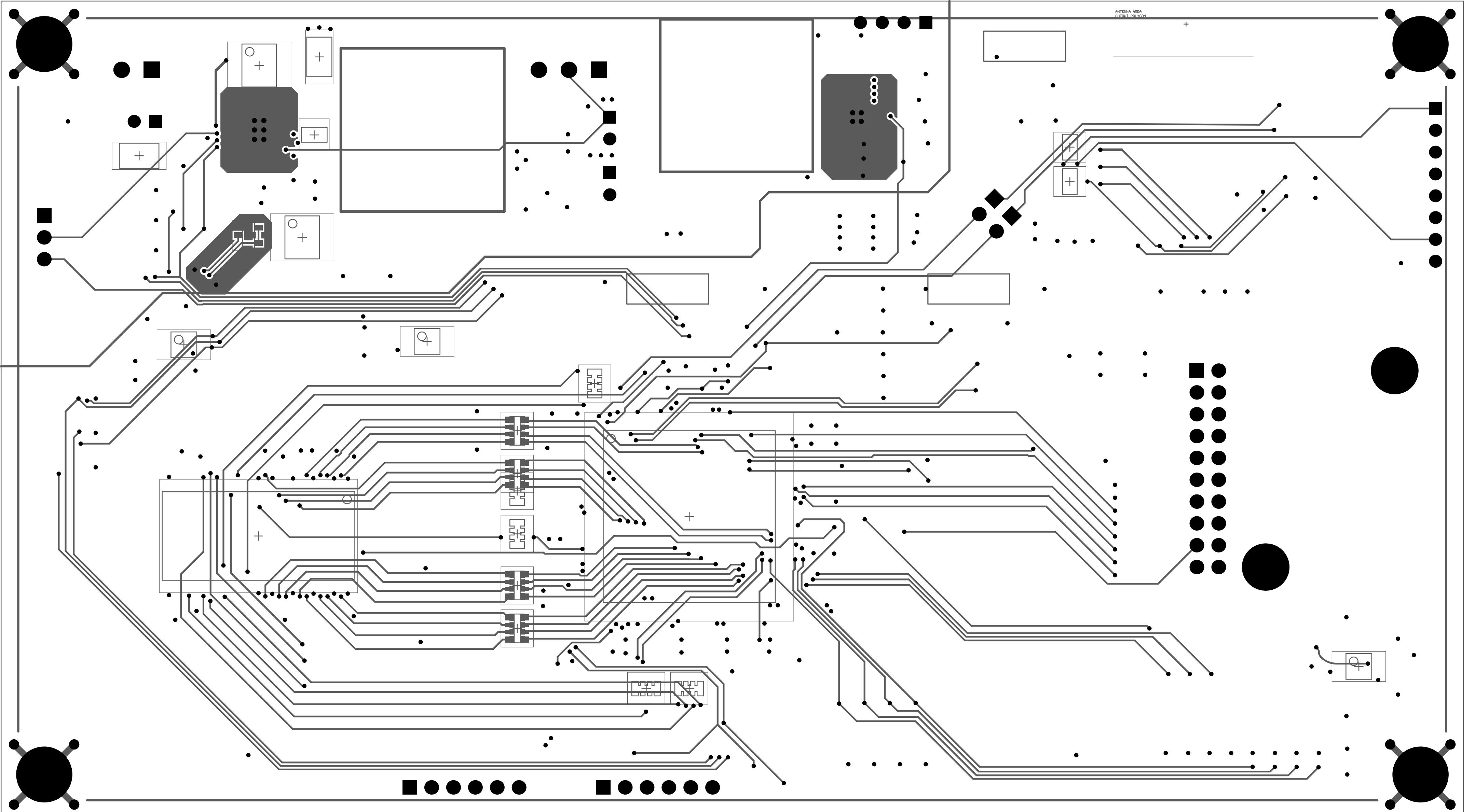
**SOLENS**

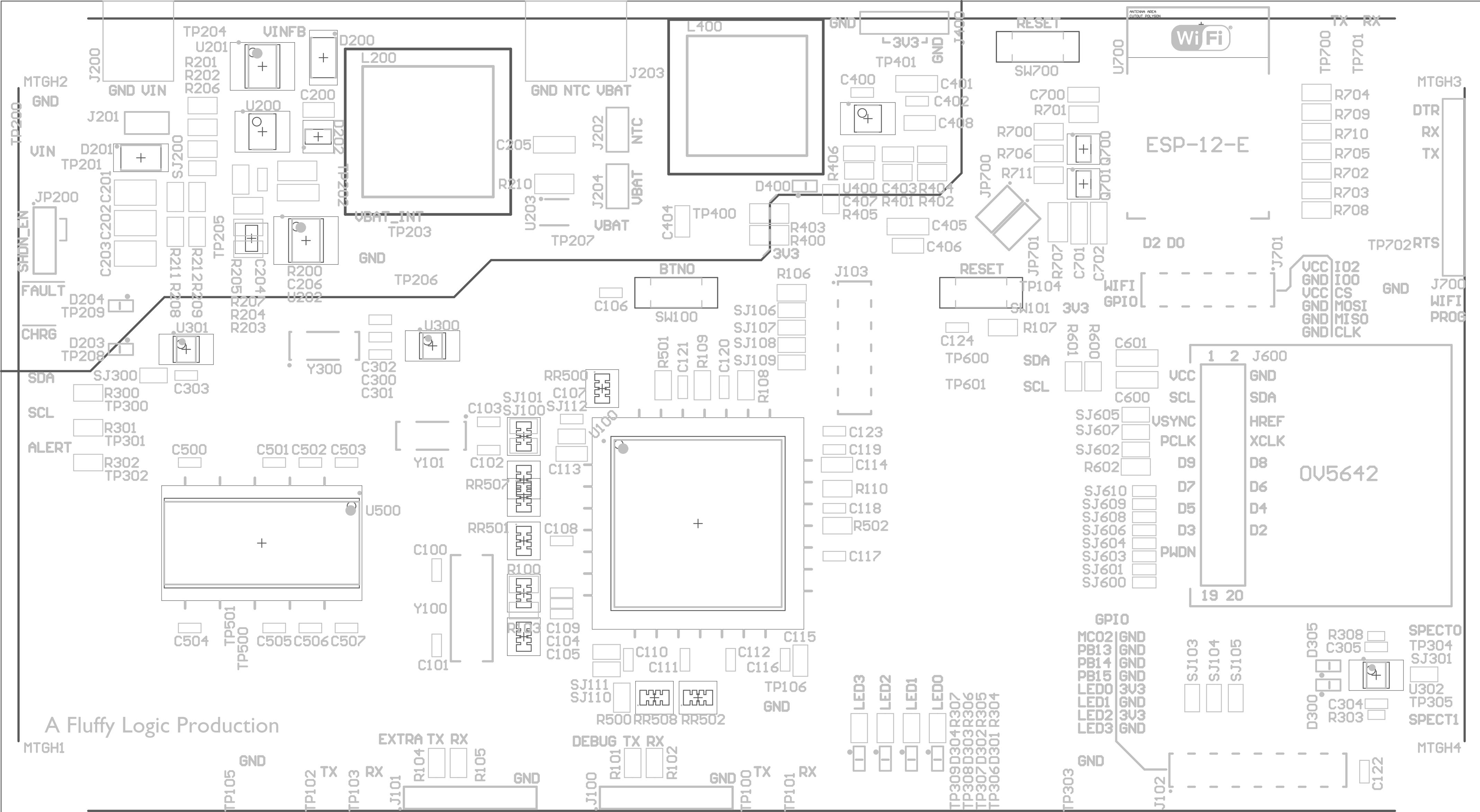


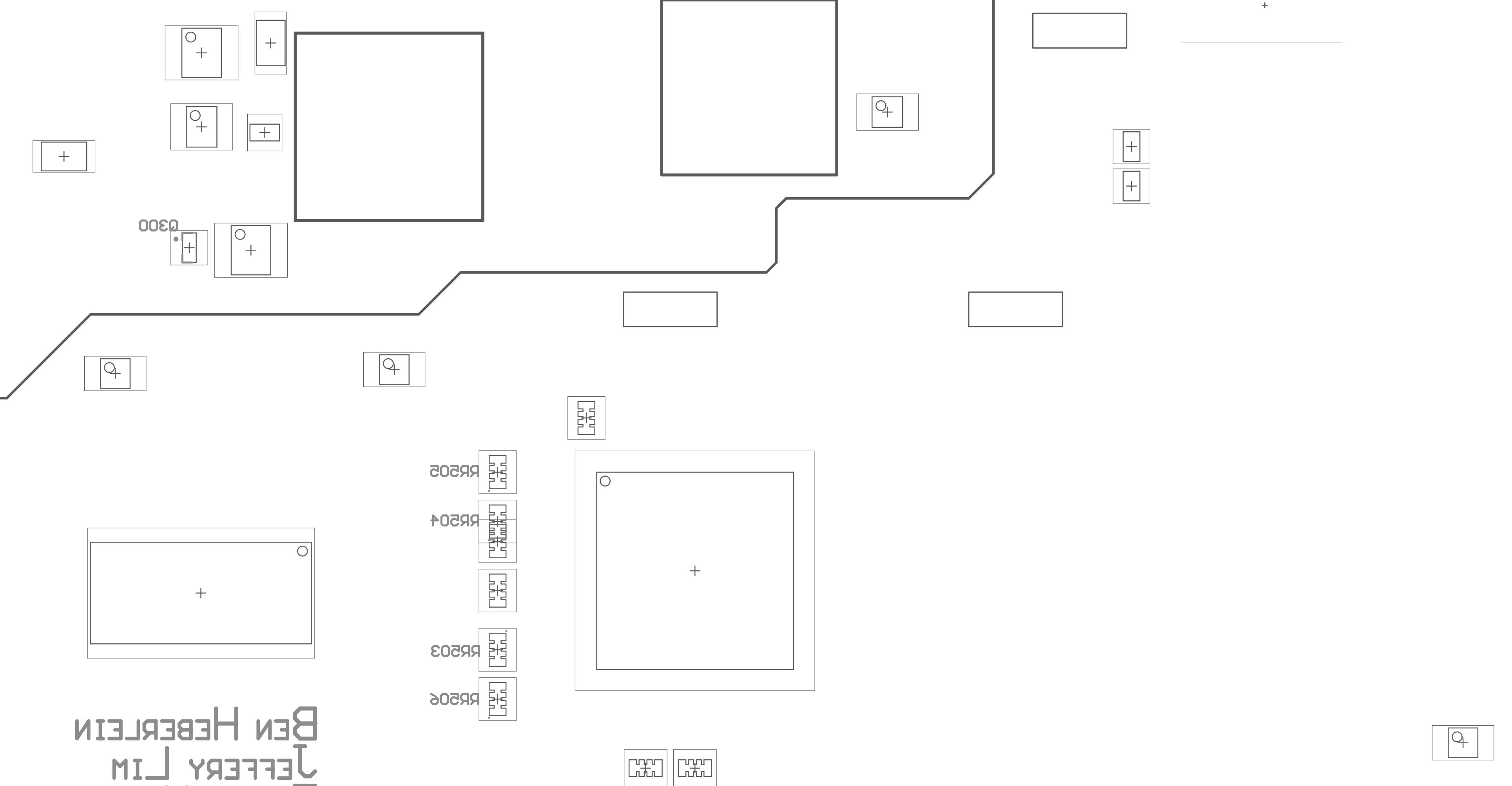




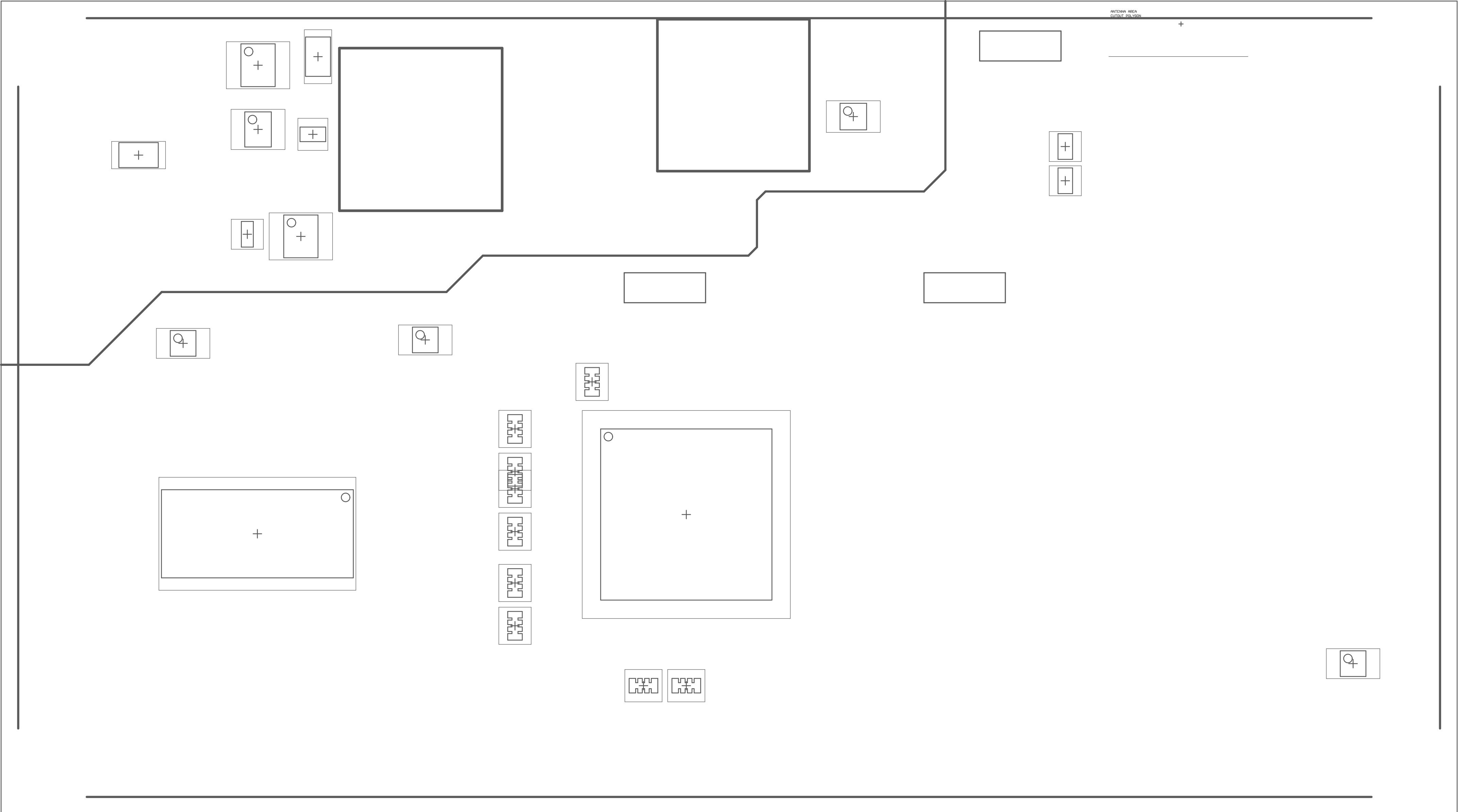


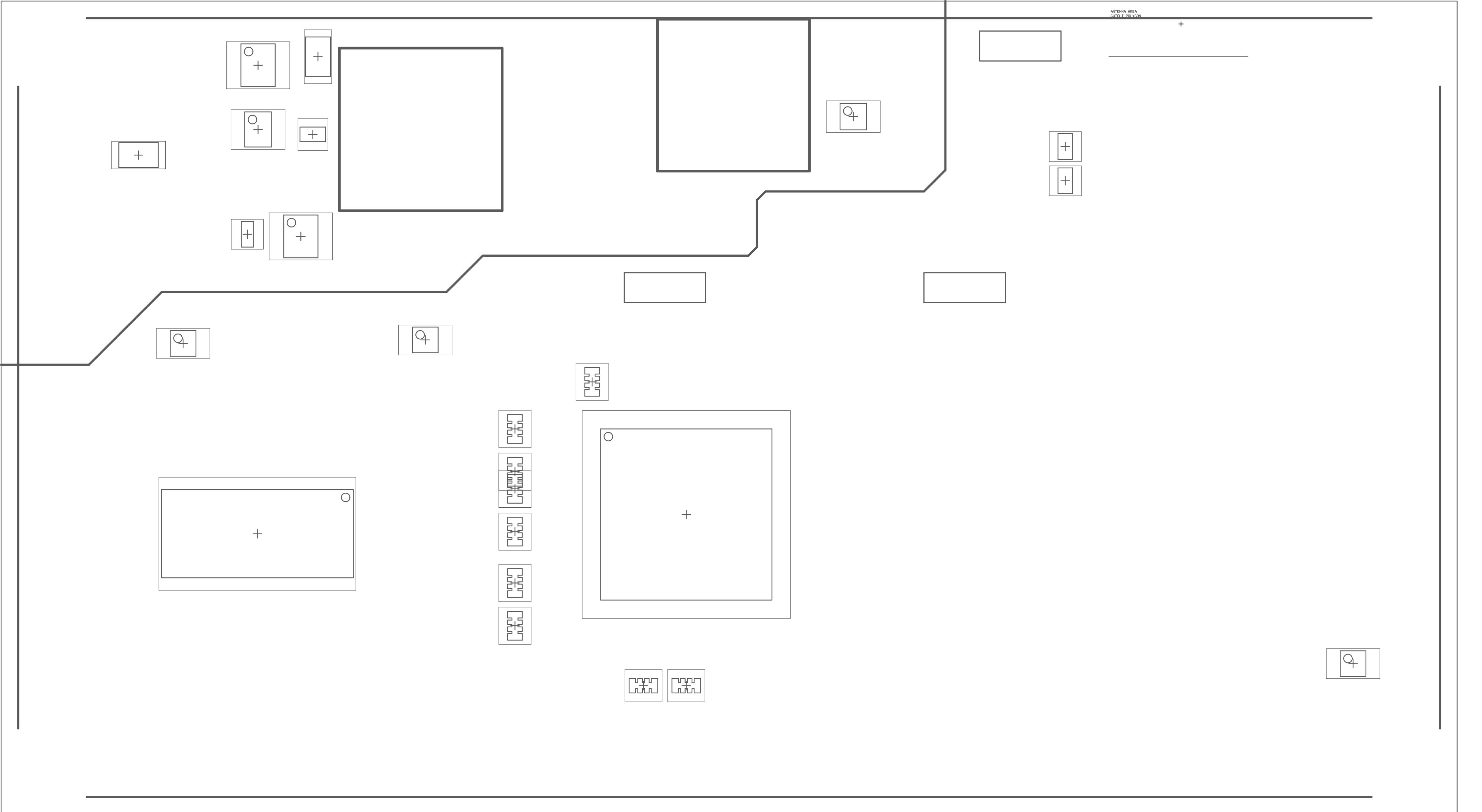






BEN HEBERLEIN  
JEFFERY LIM  
TAYLOR NGUYEN  
JEREMY RAPP  
AKIRA YOUNGBLOOD





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